

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	8	metalizing with substrate and electrode and interconnect and (adhesive or resin or epoxy) and photoresist and dielectric and holes and capacitor and resistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 15:28
L2	443	257/528.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 15:27
L3	1880	257/532.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 15:27
L4	633	257/531.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 15:27
L5	3	2 and substrate and electrode and interconnect and (adhesive or resin or epoxy) and photoresist and dielectric and holes and capacitor and resistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 15:28
L6	2	3 and substrate and electrode and interconnect and (adhesive or resin or epoxy) and photoresist and dielectric and holes and capacitor and resistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 15:28
L7	1	4 and substrate and electrode and interconnect and (adhesive or resin or epoxy) and photoresist and dielectric and holes and capacitor and resistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 15:29
L8	3176	428/209.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 15:29

L9	8	8 and substrate and electrode and interconnect and (adhesive or resin or epoxy) and photoresist and dielectric and holes and capacitor and resistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 15:30
L10	4459	428/336.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 15:29
L11	1458	428/210.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 15:30
L12	2	11 and substrate and electrode and interconnect and (adhesive or resin or epoxy) and photoresist and dielectric and holes and capacitor and resistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 15:30
L13	472	361/306.3.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 15:30
L14	4	13 and substrate and electrode and interconnect and (adhesive or resin or epoxy) and photoresist and dielectric and holes and capacitor and resistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 15:37
L15	0	("2005/0175938").URPN.	USPAT	OR	OFF	2005/08/18 15:36
L16	673	430/319.ccls.	USPAT	OR	OFF	2005/08/18 15:37
L17	0	16 and substrate and electrode and interconnect and (adhesive or resin or epoxy) and photoresist and dielectric and holes and capacitor and resistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 15:37
L18	1039	430/314.ccls.	USPAT	OR	OFF	2005/08/18 15:37
L19	677	430/318.ccls.	USPAT	OR	OFF	2005/08/18 15:37

L20	1	18 and substrate and electrode and interconnect and (adhesive or resin or epoxy) and photoresist and dielectric and holes and capacitor and resistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 15:37
L21	2	19 and substrate and electrode and interconnect and (adhesive or resin or epoxy) and photoresist and dielectric and holes and capacitor and resistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 15:38